



Product Change Notification

Change Notification #: 117518 - 00
Change Title: Select Intel® Optane™ SSD 800P Series Products, PCN 117518-00, Documentation, Booklet Change
Date of Publication: March 27, 2020

Key Characteristics of the Change:

Documentation



Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	April 13, 2020
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Description of Change to the Customer:

The Intel® Optane™ SSD 800P Series SKUs listed in the products affected table below will have the booklet changed to update the EU single point of contact.


See pictures for example of before and after.

Warranty booklet change (only page 2 and the last page of the booklet change)	
<p>Old Cover page – J61009-002</p> 	<p>New Cover page – J61009-003 (no change)</p> 

Old page 2 - J61009-002

Intel Corporation
2200 Mission College Blvd
Santa Clara, CA 95054-1549 USA

EU Single Point of Contact:
Intel Corporation (UK) Ltd.
Attn: Corp. Quality
Pipers Way, Swindon, Wiltshire SN3 1RJ UK



In the EU, this symbol means that this product must not be disposed of with household waste. It is your responsibility to bring it to a designated collection point for the recycling of waste electrical and electronic equipment. For more information, please contact your local waste collection center or your point of purchase.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709A requirements, and the PCB/Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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New page 2 - J61009-003

Intel Corporation
2200 Mission College Blvd
Santa Clara, CA 95054-1549 USA

EU Single Point of Contact:
Intel Deutschland GmbH
Attn: Corp. Quality
Am Campeon 10-12, 85579 Neubiberg, Germany



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Old back page - J61009-002




J61009-002



New back page - J61009-003



J61009-003



Customer Impact of Change and Recommended Action:

There is no change to the form, fit, function, quality or reliability of the product. This change affects the warranty booklet inside the packaging.

Customers should be aware of the change and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#	TA
Intel® Optane™ SSD 800P Series (58GB, M.2 80mm PCIe 3.0, 3D XPoint™) Retail Box 10 Pack	SSDPEK1W060GAXT	962394	J76344-201
Intel® Optane™ SSD 800P Series (118GB, M.2 80mm PCIe 3.0, 3D XPoint™) Retail Box 10 Pack	SSDPEK1W120GAXT	962395	J76345-201
Intel® Optane™ SSD 800P Series (118GB, M.2 80mm PCIe 3.0, 3D XPoint™) Retail Box Single Pack	SSDPEK1W120GAX1	962396	J76346-201

PCN Revision History:

Date of Revision:

March 27, 2020

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

117518 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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